

L Number	Hits	Search Text	DB	Time stamp
3	13	((polyoxymethylene acetal polyacetal) with (backing core base substrate)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:21
4	117	(polyoxymethylene acetal polyacetal) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:45
6	1	JP-03243343-\$ DID.	DERWENT	2002/03/08 12:39
7	3	"03243343"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:41
8	47	((polyoxymethylene acetal polyacetal) with (polystyrene polyethylene)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:47
-	4	"5827788"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:15
-	4252	(decorat\$8 near5 sheet) and (floor\$6 wall\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:39
-	197	((decorat\$8 near5 sheet) same composite) and (floor\$6 wall\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:42
-	307	442/164.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:41
-	0	((decorat\$8 near5 sheet) and (floor\$6 wall\$9)) and 442/164.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:42
-	1	((decorat\$8 near5 sheet) same composite) and 442/164.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:43
-	3	(decorat\$8 near5 sheet) and 442/164.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:45
-	4588	(decorat\$8 near5 (composite sheet)) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:47

	2291	(decorat\$8 near5 (composite sheet)) same (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:50
	175	decorat\$8 same composite same sheet same (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 11:52
	31	(decorat\$8 near5 composite near5 sheet) same (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 13:51
	65	(decorat\$8 near5 composite near5 (panel sheet)) same (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 12:19
	73	(decorat\$8 near5 composite near5 (panel sheet mo\$1ld\$8)) same (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 13:48
	12	"4706431"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 12:26
	10	((decorat\$8 near5 composite near5 (panel sheet mo\$1ld\$8)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 14:00
	12	((decorat\$8 near5 composite near5 (panel sheet mo\$1ld\$8 laminate)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 14:05
	939	((decorat\$8 near5 (panel sheet mo\$1ld\$8 laminate)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 14:09
	205	((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:17
	122	(((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9)) and thick\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 14:21
	20	(((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9)) and (thick\$8 near5 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 17:07

	0	(decorat\$8 near5 (composite laminate)) and ((heat thermal\$4) near5 (cur\$9 cross\$9) near5 protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 15:02
	0	(decorat\$8 near5 composite near5 panel) and ((heat thermal\$4) near5 (cur\$9 cross\$9) near5 protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 15:09
	20	"3378433"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/06 17:22
	20	((polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and (decorat\$8 near5 (composite laminate)) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:23
	3	((polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and ((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:22
	85	((thermoplastic polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and (decorat\$8 near5 (composite laminate)) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:25
	15	((thermoplastic polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and ((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:08
	9	("3420021" "4052835" "4157756").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 10:45
	5	((thermoplastic polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and (decorat\$8 near5 (composite laminate)) and (protect\$6 near5 (cross\$9 cur\$4 thermoset\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:17
	70	(((thermoplastic polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and (decorat\$8 near5 (composite laminate)) and (wall\$9 floor\$9)) not (((thermoplastic polystyrene polyoxymethylene (polybutylene near3 terephthalate)) near7 (substrate backing core)) and ((decorat\$8 near5 (composite laminate)) same protect\$6) and (wall\$9 floor\$9))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/07 11:29
	372	((filler talc chalk bead reinforcing) same (thermoplastic polystyrene polyethylene polyvinyl)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 09:50
	14	polyoxymethylene and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 10:59

	136	((filler talc chalk bead reinforcing) same (percent part weight) same (thermoplastic polystyrene polyethylene polyvinyl)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 09:53
	53	((filler talc chalk bead reinforcing) same ((percent part) near5 weight) same (thermoplastic polystyrene polyethylene polyvinyl)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 09:57
	26	((filler talc chalk bead reinforcing) near7 (percent part) near7 weight) same (thermoplastic polystyrene polyethylene polyvinyl)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 10:00
	8	((filler talc chalk bead reinforcing) near7 (percent part) near7 weight) same (thermoplastic polystyrene polyethylene polyvinyl) same (backing core)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 10:01
	1	((polyoxymethylene paraformaldehyde) near7 (backing core substrate)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 11:02
	60	(polyoxymethylene paraformaldehyde) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:27
	8	(polyoxymethylene paraformaldehyde) same (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 11:06
	7	(polyoxymethylene acetal polyacetal) same (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 11:07
	13	((polyoxymethylene acetal polyacetal) with (backing core base substrate)) and (decorative near5 (composite laminate structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/08 12:17